

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WEI YUAN	03/05/2014
YU-SAN HSIAO	04/14/2014
SHIH-WEI HSIAO	04/14/2014
RECEIVING PARTY DATA	
Name:	HON HAI PRECISION INDUSTRY CO., LTD.
Street Address:	No. 2, Tzu Yu Street, Tu-Cheng Dist.
City:	New Taipei
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14252798
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	WEI TE CHUNG
SIGNATURE:	/WEI TE CHUNG/
DATE SIGNED:	04/15/2014
Total Attachments: 2	
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ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- 1. WEI YUAN , residing at ShenZhen, China
- 2. YU-SAN HSIAO , residing at New Taipei, Taiwan
- 3. SHIH-WEI HSIAO , residing at New Taipei, Taiwan
- 4. _____ , residing at _____
- 5. _____ , residing at _____
- 6. _____ , residing at _____
- 7. _____ , residing at _____
- 8. _____ , residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **HON HAI PRECISION INDUSTRY CO., LTD.** having a principal place of business at **No. 2, Tzu Yu Street, Tu-Cheng Dist., New Taipei City, Taiwan, R.O.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **ELECTRICAL CONNECTOR HAVING IMPROVED INSULATIVE HOUSING** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>Wei Yuan</u> WEI YUAN	<u>03/05/2014</u> Date
2.	<u>YU SAN HSIAO</u> YU-SAN HSIAO	<u>04/14/2014</u> Date
3.	<u>Shih-Wei Hsiao</u> SHIH-WEI HSIAO	<u>04/14/2014</u> Date
4.	_____	_____ Date
5.	_____	_____ Date
6.	_____	_____ Date
7.	_____	_____ Date
8.	_____	_____ Date
9.	_____	_____ Date